

Buildup for Mindteck
mind-03aug2k11-11799

0.0350	copper plating layer 1		
0.0700	copper foil layer1	Signal	29.0635 mil traces 50 ohms single ended 8 mil traces 7.0339 mil seperation 100 ohms differential
	Prepreg 1-2		
0.0350	copper foil layer 2	Signal	17.5010 mil traces 50 ohms single ended 8 mil traces 6.6430 mil seperation 100 ohms differential
	Core 2-3		
0.0350	copper foil layer 3	Plane	
	Prepreg 3-4		
0.0350	copper foil layer 4	Signal	8.5220 mil traces 50 ohms single ended 5.2535 mil traces 6.7465 mil seperation 100 ohms differential
	Core 4-5		
0.0350	copper foil layer 5	Plane	
	Prepreg 5-6		
0.0350	copper foil layer 6	Plane	
	core 6-7		
0.0350	copper foil layer 7	Signal	8.5220 mil traces 50 ohms single ended 5.2535 mil traces 6.7465 mil seperation 100 ohms differential
	pregreg 7-8		
0.0350	copper foil layer 8	Plane	
	core 8-9		
0.0350	copper foil layer 9	Signal	17.5010 mil traces 50 ohms single ended 8 mil traces 6.6430 mil seperation 100 ohms differential
	pregreg 9-10		
0.0700	copper foil layer 10	Signal	29.0635 mil traces 50 ohms single ended 8 mil traces 7.0339 mil seperation 100 ohms differential
0.0350	copper plating layer 8		
3.0000	total pcb thickness in mm		

Disclaimer: This stack-up has assumptions regarding the copper area per layer, as well as prepreg distance & dielectric constants. An impedance tolerance of +/- 10% can only be achieved if we adjust the trace width & prepreg height to meet the impedance requirement after receipt of the gerber files.